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## **Wed-Af-Po3.21-06 [72]: Fundamental study on the effect of Zn addition into Cu matrix in internal tin Nb<sub>3</sub>Sn conductors**

*Wednesday, 25 September 2019 14:00 (2 hours)*

As a new approach to enhance the  $J_c$  property, we have been studying the element addition into the Cu matrix in the internal tin Nb<sub>3</sub>Sn conductors. We have shown so far that Zn addition promotes the Nb<sub>3</sub>Sn layer formation, compared to the non-doped Cu matrix Nb<sub>3</sub>Sn wires.

In this work, we concentrated to investigate the effect of Zn addition on the microstructure during the heat treatment in detail thorough fundamental study. First, various single Cu-Zn/Sn composites were prepared and then their reaction behaviors were observed with respect to the heat treatment condition. The most interesting finding was that the Cu-Zn/Sn diffusion couples resulted in a significantly different reaction behavior from the Cu/Sn diffusion couple. For example, in the Cu/Sn couple,  $\epsilon$  phase widely forms together with  $\eta$  phase at the reaction layer at 400 °C, while in the Cu-Zn/Sn couple, another ternary Cu-Sn-Zn phase (presumably  $\beta$ -CuZn) forms adjacent to  $\epsilon$  phase. This was considerably interesting, because this ternary phase is quite solid and no void is present, while the  $\epsilon$  phase contains many voids. The suppression of void formation should be important for the improvement of Cu/Sn interdiffusion during the pre-annealing in the multifilamentary precursor wires. In our laboratory scale Nb<sub>3</sub>Sn multifilamentary wire samples, the  $J_c$  in the Cu-Zn matrix samples is appreciably better than that in the Cu matrix sample, which would be attributed to the improvement of Sn diffusivity in the pre-annealing process. In addition, we investigated optimum Zn content in the Cu matrix, the grain size and the influence of the filament barrier thickness and so on.

The Zn addition into the Cu matrix is fairly interesting for further  $J_c$  improvement of the Nb<sub>3</sub>Sn conductors in terms of uniform Sn diffusion across the matrix and acceleration of the Nb<sub>3</sub>Sn layer formation.

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